Form PTO-1595 (Rev. 03/ 01) DMB No. 0651-0027 (exp. 5/31/2002) 102745924	U.S. DEPARTMENT OF COMMERCE U.S. Patent and Trademark Office
To the Honorable Commissioner of Patents and Trademarks: F	Please record the attached original documents or copy thereof
1. Name of conveying party(ies):	2. Name and address of receiving party(ies)
Yoshiki Hishiro 5.7.04	Name: MICRON TECHNOLOGY, INC.
	Internal Address:
	Street Address:
Additional name(s) of conveying party(ies) Additional name(s) of conveying party(ies) Yes x No	Missau Tashaslam Inc
3. Nature of Conveyance:	Micron Technology, Inc.
x Assignment Merger	
Security Agreement Change of Name	City: Boise
Other	State: ID Zip: 83707-0006
Execution Date: April 29, 2004	Additional name(s) & Yes x No
<u> </u>	address(es) attached:
Application number(s) or patent number(s):	11841647
If this document is being filed together with a new application, the ex	xecution date of the new application is: April 29, 2004
A. Patent Application No.(s):	B. Patent No.(s):
This application	
Additional numbers attach	ned? Yes X No 6. Total number of applications and
concerning document should be mailed:	patents involved:1
Name: Thomas J. D'Amico DICKSTEIN SHAPIRO MORIN & OSHINSKY LLF	7. Total fee (37 CFR 3.41) \$40.00
Internal Address: Atty. Dkt.: M4065.1021/P1021	Enclosed
Street Address: 101 L Street NW	Authorized to be charged to deposit account
10 I C Street NVV	x Authorized to be charged to credit card
	(Form 2038 enclosed)
City: State: Zip:	8. Deposit account number:
Washington DC 20037-1526	04-1073 (Attach duplicate copy of this page if paying by deposit account)
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To the best of my knowledge and belief, the foregoing infis a true copy of the original document.	ormation is true and correct and any attached copy
Thomas J. D'Amico, #28,371	May 7, 2004
Name of Person Signing	Signature Date
Total number of pages including cover sheet, attac	hments, and documents: 3
ESSEM1 00000036 10840647 40.00 DF	

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Docket No.: M4065.1021/P1021

ASSIGNMENT AND AGREEMENT

For value received, I, Yoshiki Hishiro, hereby sell, assign and transfer to Micron Technology, Inc., a corporation of the State of Delaware, having an office at 8000 S. Federal Way, Boise, Idaho 83706-9632, U.S.A., and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to an invention entitled RESIST PATTERN AND REFLOW TECHNOLOGY, described in an application for Letters Patent of the United States, executed by me of even date herewith, and all the rights and privileges in said application and under any and all Letters Patent that may be granted in the United States for said inventions; and I also concurrently hereby sell, assign and transfer to Micron Technology, Inc. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

I authorize Micron Technology, Inc. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from me, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

I hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Micron Technology, Inc. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

I request that any and all patents for said inventions be issued to Micron Technology, Inc. in the United States and in all countries foreign to the United States, or to such nominees as Micron Technology, Inc. may designate.

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PATENT REEL: 015313 FRAME: 0974

Docket No.: M4065.1021/P1021

I agree that, when requested, I shall, without charge to Micron Technology, Inc. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

Myshiki Hishiro

Date: April 29, 2004

United States of America

State of <u>Idaho</u>
County of <u>Ada</u>

29 11 19 11

On this 272 day of (1) , 3009, before me personally came Yoshiki Hishiro, to me known to be the individual described in and who executed the foregoing instrument, and acknowledged execution

of the same.

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RECORDED: 05/07/2004

PATENT REEL: 015313 FRAME: 0975